

SOT802-2

plastic thin fine-pitch ball grid array package; 160 balls; body
9 x 13 x 0.7 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA160
Package type industry code	TFBGA160
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	13-7-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	12.9	-	13	13.1	mm
E	package width	8.9	-	9	9.1	mm
A	seated height	[tbd]	-	1.15	1.15	mm
A ₂	package height	0.65	-	0.7	0.8	mm
n ₂	actual quantity of termination	-	-	160	-	



2. Package outline

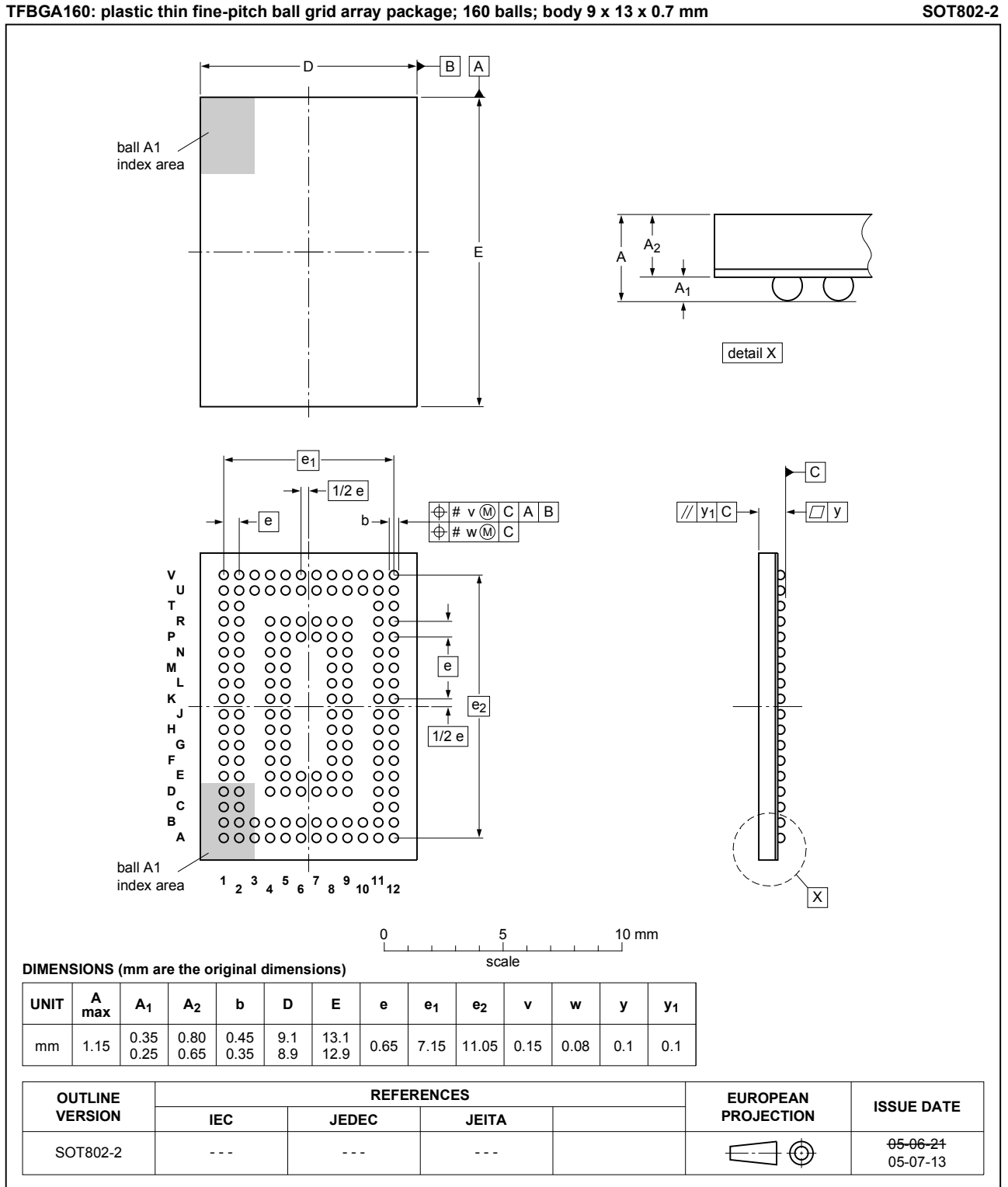


Fig. 1. Package outline TFBGA160 (SOT802-2)

3. Soldering

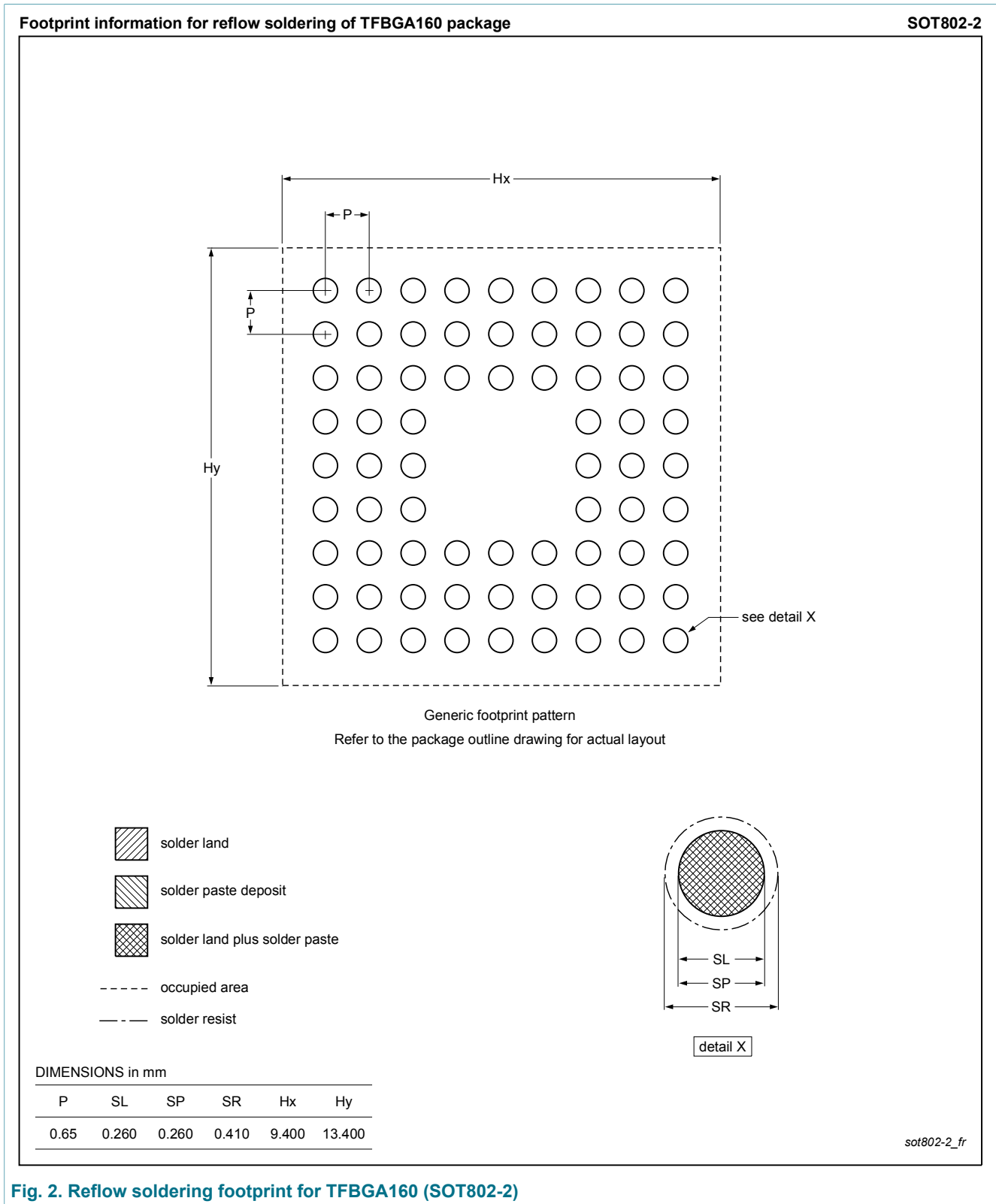


Fig. 2. Reflow soldering footprint for TFBGA160 (SOT802-2)

4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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